


Updated: 23/05/05	TECHNICAL DATA SHEET	
Ref. : Alloy	<u>Sn99 Ag0.3 Cu0.7</u>	
Created: 20/07/04	<u>LEAD FREE ALLOY</u>	

1 – GENERAL CHARACTERISTICS:

Lead Free alloy for soldering printed circuits, produced from very high quality metals.

2 – CHEMICAL CHARACTERISTICS:

- 2.1 Amount of Tin : 99 +/- 0.3%
 2.2 Amount of Silver : 0.3 +/- 0.1 %
 2.3 Amount of Copper : 0.7 +/- 0.2%
 2.4 Tin and Silver Copper for first melting, purity > 99.95%
 2.5 Maximum content of impurities: see below :

Cd	Sb	Bi	Fe	Zn	Al	As	Pb	others
<0.002 %	<0.05 %	<0.01 %	<0.02 %	<0.001 %	<0.001 %	<0.01 %	<0.05 %	<0.05 %

3- PHYSICAL CHARACTERISTICS:

- 3.1 Melting point : 217°C – 228°C
 3.2 Working temperature : 260 to 270°C.
 3.3 Specific Weight : 7.3

4 – SUPPLIED AS :

- 4.1 Bars : Extruded Bars or sticks in cartons of 20 Kg.
 (Exact Tare weight stated).
 4.2 Wire : On spools of 15 Kgs. (others please contact us)
 4.4 Quality insurance : Certificates of conformity can be supplied with each lot if required.
 4.5 Labelling : Cartons/containers labels show manufactured lot N° and Alloy.

5 – STORAGE :

- 5.1 - Original packaging, at an average temperature of 20°C
 12 months for flux cored wires.